Call for Proposals CIES Collaborative Research Center for Innovative Integrated Electronic Systems, Tohoku University

Aim	CIES aims to contribute to the enhancement of global competitiveness in the field of next-generation integrated electronics systems, and work toward the creation of practical applications and new industries, through the research and development of innovative devices and its integrated electronic systems and the establishment of a consortium for this field under the international collaboration among industries, universities and government. "CIES Collaborative Research" promotes advanced R&D with cooperation of the CIES researchers in wide range of fields from upstream (physics and economic theory, materials, process, device, etc.) to – downstream (system, application, and marketing, etc.) in the next-generation integrated electronics for accelerating the integration and innovation.
R&D areas	The proposals in the following priority R&D areas in CIES are applicable. (1)Spintronics (2)Power devices (3) Information theory and its application (4)Edge computing (5)Car electronics Application Edge Car Electronics Brain-type Intelligent System
	(6)Brain-type intelligent system (7) Industry-academia collaboration using IPs, research for venture support and regional revitalization Base Information theory and application Industry-academia collaboration using IP Research for supporting venture and regional Revitalization
Support	Four types of research proposals are available. The research period of each type is within the fiscal year, and not only using CIES facilities but collaboration researches with CIES researchers are essential. Type I: Proposal of industry-academic collaboration Research theme for the purpose of developing it to an industry-academic collaboration. R&D grant: 2,000,000yen/fiscal year (It may be reduced depending on the review results) Type II: Support for young researchers Research theme for project leaders under 45 years old. R&D grand: 1,500,000yen/fiscal year(It may be reduced depending on the review results)

	Type III: Research meeting Exploratory research theme R&D grand: 1,000,000yen/fiscal year (It may be reduced depending on the review results) Type IV: Industry-university collaborative project using CIES facilities Research theme for the purpose of developing it to a large-scale industry-academic collaboration. R&D grant: Maximum 5,000,000yen/fiscal year (On this program, a supporting rate enforces it as 50% of matching fund. Please note that the supporting rate may become less than 50% when the total amount increases.)
Research period	From the adoption decision notice (Scheduled for October 2018) through March 31, 2019
Possible candidates	Researchers who belong universities, national research institutes and private enterprises, etc. The university-academic collaborations or the international collaborations are preferable. Independent proposals from universities, research organizations and companies in Japan are acceptable.
Renewal	Renewable based on the same research project as the previous year, but the total research period is within three years.
Deadline for applications	September 14, 2018 (The proposals must arrive) ※Additional proposals might be accepted.
Result announcement	The middle of October , 2018 (tentative)
Application materials	The files of the following documents (pdf) should be sent to the following e-mail address and the printed-out documents should be sent via regular mail to the following address on the last page. Please note that the application documents will not be returned. (1) Application form for CIES collaborative research (2) Acceptance letter for CIES collaborative research (from your institute)
	The result will be announced by CIES collaborative research selection committee. When it is accepted, the project leader and co-researchers will be commissioned as "Collaborative researcher of Center for Innovative Integrated Electronic System, Tohoku University".
Number of accepted proposals	Number of accepted proposals in FY2017 Type I: none / Type II: 2 / Type III: none / Type IV: none

Others (Results and report)

1. The handling of intellectual property rights

Tohoku University Regulation regarding collaborative research will be applied as standard. [http://www.rpip.tohoku.ac.jp/files/kyoudou.pdf]

2. Expenses

Travel expenses in order to visit CIES for research and workshop, and the budget for promoting research will be provided. The amount will be decided depending on the number of accepted proposals.

3. Accommodation

Please arrange it by yourself as CIES has no facilities.

4. Submission of the research report

Project leader should submit a research report within 3 pages on A4 paper by March 31, 2019.

XThe form will be sent to you later.

A hearing regarding Type IV will be held in the end of the fiscal year. It may be also organized for both Type I and II. Additionally a questionnaire will be excluded.

5. Acknowledgement

When you publish achievements of CIES Collaborative Research, please add the following sentences as acknowledgement. Please submit one copy to CIES.

- (1) Part of this work was carried out under the CIES Collaborative Research of the Center for Innovative Integrated Electronic Systems, Tohoku University.
- (2) This work was performed in the CIES Collaborative Research of the Center for Innovative Integrated Electronic Systems, Tohoku University.
- (3) We acknowledge the stimulated discussion in the meeting of the CIES Collaborative Research of the Center for Innovative Integrated Electronic Systems, Tohoku University.
- (4) This conference was partially supported by the CIES Collaborative Research of the Center for Innovative Integrated Electronic Systems, Tohoku University.

6. Presentation of achievements

CIES Collaborative Research accomplishments presentation will be held in the end of the fiscal year. We may request you to present the achievement.

7. The handling of R&D

R&D is one of the projects of CIES. Please follow the regulations of CIES during the term.

Contact

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